

| External_Type  | Material_Group   | Substances                                    | CAS_Number      | Mass             | Mass_Percentage_in_Leaf | Massmg        |
|----------------|------------------|-----------------------------------------------|-----------------|------------------|-------------------------|---------------|
| Die            | Doped silicon    | Silicon (Si)                                  | 7440-21-3       | 0.33836          | 100.0                   | 0.77          |
|                |                  |                                               | <b>Subtotal</b> | <b>0.33836</b>   | <b>100</b>              | <b>0.77</b>   |
| Post-plating   | Tin solder       | Bismuth (Bi)                                  | 7440-69-9       | 0                | 0.0                     | 0             |
|                | Tin solder       | Tin (Sn)                                      | 7440-31-5       | 1.61692          | 99.99                   | 3.67963       |
|                | Tin solder       | Copper (Cu)                                   | 7440-50-8       | 0                | 0.0                     | 0             |
|                | Tin solder       | Lead (Pb)                                     | 7439-92-1       | 0.00016          | 0.01                    | 0.00037       |
|                | Tin solder       | Antimony (Sb)                                 | 7440-36-0       | 0                | 0.0                     | 0             |
|                |                  |                                               | <b>Subtotal</b> | <b>1.61708</b>   | <b>100</b>              | <b>3.68</b>   |
| Lead Frame     | Copper alloy     | Misc. Phosphor compounds (generic)            | 7723-14-0       | 0.00789          | 0.02                    | 0.01794       |
|                | Copper alloy     | Iron (Fe)                                     | 7439-89-6       | 0.03154          | 0.08                    | 0.07178       |
|                | Copper alloy     | Copper (Cu)                                   | 7440-50-8       | 39.30696         | 99.7                    | 89.45084      |
|                | Pure metal layer | Silver (Ag)                                   | 7440-22-4       | 0.07885          | 0.2                     | 0.17944       |
|                |                  |                                               | <b>Subtotal</b> | <b>39.42524</b>  | <b>100</b>              | <b>89.72</b>  |
| Adhesive       | Polymer          | Paraffin wax                                  | 8002-74-2       | 0.21971          | 20.0                    | 0.5           |
|                | Polymer          | Epoxy resin system                            |                 | 0.08789          | 8.0                     | 0.2           |
|                | Filler           | Silver (Ag)                                   | 7440-22-4       | 0.79097          | 72.0                    | 1.8           |
|                |                  |                                               | <b>Subtotal</b> | <b>1.09857</b>   | <b>100</b>              | <b>2.5</b>    |
| Mould Compound | Polymer          | Tetrabromobisphenol A/Epichlorohydrin polymer | 40039-93-8      | 1.43769          | 2.5                     | 3.27175       |
|                | Polymer          | Phenol Formaldehyde resin (generic)           | 9003-35-4       | 4.31307          | 7.5                     | 9.81525       |
|                | Filler           | Silica -amorphous-                            | 7631-86-9       | 21.2778          | 37.0                    | 48.4219       |
|                | Pigment          | Carbon black                                  | 1333-86-4       | 0.28754          | 0.5                     | 0.65435       |
|                | Polymer          | Epoxy resin system                            |                 | 8.62614          | 15.0                    | 19.6305       |
|                | Filler           | Silicon Dioxide (SiO2)                        | 14808-60-7      | 21.2778          | 37.0                    | 48.4219       |
|                | Flame retardant  | Antimony Trioxide (Sb2O3) - cas no. 1309-64-4 | 1309-64-4       | 0.28754          | 0.5                     | 0.65435       |
|                |                  |                                               | <b>Subtotal</b> | <b>57.50758</b>  | <b>100</b>              | <b>130.87</b> |
| Wire           | Pure metal       | Copper (Cu)                                   | 7440-50-8       | 0.01318          | 100.0                   | 0.03          |
|                |                  |                                               | <b>Subtotal</b> | <b>0.01318</b>   | <b>100</b>              | <b>0.03</b>   |
|                |                  |                                               | <b>Total</b>    | <b>100.00001</b> | <b>100</b>              | <b>227.57</b> |

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